



3D Printing of MEMS Technology

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Message from the Guest Editor

3D printing belongs to the emerging technologies of our time. While previously mostly used for rapid prototyping, the technology has long entered rapid production, especially for complicated objects or small lot sizes. Most recently, new 3D printing technologies enable printing smallest features on micro- or even nano-scales. At the same time, well-known problems like the waviness of fused deposition modeling (FDM) printed parts, the missing long-term stability of some typical printing materials or reduced mechanical properties of 3D printed objects still exist.

This special issue focusses on all topics dealing with 3D printing of micro-electro-mechanical systems (MEMS), such as new or advanced features enabled by 3D printing as compared to conventional technologies, but also the still existent challenges of using 3D printing technologies for MEMS and new approaches how to overcome them.





Editor-in-Chief

Message from the Editor-in-Chief

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